

Title (en)

Complementary semiconductor device comprising two heterostructure field-effect transistors with strained channel layer

Title (de)

Komplementäre Halbleiteranordnung mit zwei Heterostruktur-Feldeffekttransistoren mit verspannter Kanalschicht

Title (fr)

Dispositif semi-conducteur complémentaire comprenant deux transistors à effet de champ à hétérostructure et couche de canal contrainte

Publication

**EP 0921575 A2 19990609 (EN)**

Application

**EP 98122863 A 19981202**

Priority

JP 33272697 A 19971203

Abstract (en)

A MISFET having extremely high mobility comprising a first silicon layer (Si layer)(12), a silicon layer containing carbon (Si<sub>1-y</sub>Cy layer)(13) and an optional, second silicon layer (Si layer)(14) stacked in this order on a silicon substrate (10). The carbon content and thickness of the Si<sub>1-y</sub>Cy layer acting as a channel layer of the MISFET are such that said Si<sub>1-y</sub>Cy layer is under tensile strain whereby the conduction and valence bands thereof are split. Therefore, charge carriers having a smaller effective mass, which have been induced by an electric field applied to an insulated gate electrode (15,16), are confined in the Si<sub>1-y</sub>Cy layer, and move in the channel direction. Furthermore, if the silicon layer containing carbon is made of Si<sub>1-x-y</sub>GexCy, a structure suitable for a high-performance CMOS device can be formed. Alternatively, the silicon layers may contain a slight amount of carbon or germanium, and a Schottky gate may be provided whereby a MESFET is achieved. <IMAGE>

IPC 1-7

**H01L 29/778; H01L 29/78; H01L 29/165; H01L 29/161**

IPC 8 full level

**H01L 21/338** (2006.01); **H01L 21/762** (2006.01); **H01L 29/10** (2006.01); **H01L 29/161** (2006.01); **H01L 29/778** (2006.01); **H01L 29/78** (2006.01); **H01L 29/80** (2006.01); **H01L 29/812** (2006.01)

CPC (source: EP KR US)

**H01L 29/1054** (2013.01 - EP US); **H01L 29/161** (2013.01 - EP US); **H01L 29/7782** (2013.01 - EP US); **H01L 29/7786** (2013.01 - EP US); **H01L 29/78** (2013.01 - KR); **H01L 29/802** (2013.01 - EP US)

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CN100342494C; EP1378943A4; EP1676296A4; DE102004039981B4; US6635909B2; EP1102327A3; US8816391B2; US7368356B2; WO03069658A3; WO0233759A1; US6498359B2; US6872625B2; US9768305B2; US10269970B2; US8455860B2; US8674408B2; US8617976B2; US9006788B2; US6984844B2; US6821856B2; US6995397B2; WO03063254A1; WO03028110A1; US7235822B2; US7005333B2; US6767793B2; US6844227B2; US7244972B2; WO2005064683A1; WO02052652A1; WO03081640A3; US7417248B2; US7094671B2; US8674341B2; US8927371B2; US9590068B2; US10109748B2

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**EP 98122863 A 19981202**; CN 98123113 A 19981203; JP 33360198 A 19981125; KR 19980052737 A 19981203; TW 87119916 A 19981201; US 20309898 A 19981202